PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
Stylesheet Version v1.2

EPAS ID: PAT3385718

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT

CONVEYING PARTY DATA

Name	Execution Date
DANIEL BILLINGSLEY	04/14/2015
ROBERT M. KENNEDY	04/14/2015
WENHONG SUN	06/05/2015
RAKESH JAIN	04/14/2015
MAXIM S. SHATALOV	04/15/2015
ALEXANDER DOBRINSKY	05/11/2015
MICHAEL SHUR	04/15/2015
REMIGIJUS GASKA	05/11/2015

RECEIVING PARTY DATA

Name:	Sensor Electronic Technology, Inc.
Street Address:	1195 Atlas Road
City:	Columbia
State/Country:	SOUTH CAROLINA
Postal Code:	29209

PROPERTY NUMBERS Total: 2

Property Type	Number
Application Number:	14686845
Application Number:	61979717

CORRESPONDENCE DATA

Fax Number: (518)514-1360

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 5187553658
Email: national@labattlaw.com
Correspondent Name: JOHN W LABATT
Address Line 1: PO BOX 630
Address Line 4: VALATIE, NEW YORK 12184

ATTORNEY DOCKET NUMBER:	SETI-0128
NAME OF SUBMITTER:	JOHN W. LABATT

SIGNATURE:	/John W. LaBatt/
DATE SIGNED:	06/06/2015

Total Attachments: 18
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ASSIGNMENT OF PATENT APPLICATIONS

This Agreement is entered into and effective as of April 14, 2015, by and between Sensor Electronic Technology, Inc., a New York corporation, having an address of 1195 Atlas Road, Columbia, SC 29209 (Assignee) and the below named Inventors (Assignors).

WHEREAS each Assignor has contributed to the conception of an invention and/or improvement described in the following, collectively referred to as the "Patent Applications":

(a) a U.S. Provisional Application No. 61/979,717, filed on 15 April 2014; and

(b) a nonprovisional utility patent application for filing in the United States, titled "Semiconductor Heterostructure with Stress Management" and identified as Attorney Docket No. SETI-0128-US, at LaBatt, LLC, PO Box 630, Valatie, NY 12184; and

(c) any and all applications claiming the benefit of any of the above-referenced applications and any and all continuations, continuations-in-part, divisionals, and renewals of and substitutes for any of the above-referenced applications;

WHEREAS Assignors desire to sell, assign, and transfer all of their rights, title, and interest, for all countries in and to the Patent Applications and the inventions and improvements described therein to Assignee; and

WHEREAS Assignee desires to obtain all of the rights title, and interest, for all countries in and to the Patent Applications and the inventions and improvements described therein as the sole owner of the Patent Applications.

NOW THEREFORE, for and in consideration of good and valuable consideration, the receipt and sufficiency of which is hereby expressly acknowledged, the parties agree as follows:

1. Assignors hereby sell, assign, and otherwise transfer unto Assignee, and its successors, assigns and legal representatives, the rights, title and interest, for all countries in and to the Patent Applications and the inventions and improvements described therein and any and all rights and privileges under any and all Letters Patent that may be granted therefor in any country, and any reissues, or reexaminations, or extensions of any such Letters Patent.

2. Assignors request that any and all Letters Patent for the inventions and improvements described in the Patent Applications be issued to the Assignee, its successors, assigns and legal representatives, or to such nominees as the Assignee may designate.

3. Assignors authorize and empower the Assignee, its successors, assigns and legal representatives or nominees, to invoke and claim for any Patent Application or other form of protection for the inventions and improvements described in the Patent Applications, the benefit of the right of priority provided by the International Convention for the Protection of Industrial Property, as amended, or by any convention which may henceforth be substituted for it, and to invoke and claim such right of priority without further written or oral authorization from the Assignors.

4. Assignors hereby consent that a copy of this Agreement shall be deemed a full legal and formal equivalent of any assignment, consent to file, or like document, which may be required in any country for any purpose and more particularly as proof of the right of the Assignee, its successors, assigns and legal representatives, or to such nominees as the Assignee may designate to claim the aforesaid benefit of the right of priority provided by the International Convention or any convention which may henceforth be substituted for it.

5. Assignors covenant with the Assignee, its successors, assigns and legal representatives, that the rights and property herein conveyed are free and clear of any encumbrance, and that Assignors have full right to convey the same as herein expressed.

6. This Agreement and the rights and obligations of the parties hereunder shall be construed in accordance with and governed by the Law of the State of New York without giving effect to the conflict of law principles thereof.

7. This Agreement may be executed in any number of counterparts, each of which shall be deemed an original but all of which together shall constitute one and the same agreement.

[Signature page follows]

IN WITNESS WHEREOF, the parties have executed this agreement below.

By Sensor Electronic Technology, Inc.:

Signature: /__________________________/ Date: __________________
Michael Shur, Vice President

By each Inventor:

Signature: /__________________________/ Date: April 14, 2015
Daniel Billingsley, an individual residing in Austin, TX, US

Signature: /__________________________/ Date: __________________
Robert M. Kennedy, an individual residing in Columbia, SC, US

Signature: /__________________________/ Date: __________________
Wenhong Sun, an individual residing in Columbia, SC, US

Signature: /__________________________/ Date: __________________
Rakesh Jain, an individual residing in Columbia, SC, US

Signature: /__________________________/ Date: __________________
Maxim S. Shatalov, an individual residing in Columbia, SC, US

Signature: /__________________________/ Date: __________________
Alexander Dobrinsky, an individual residing in Loudonville, NY, US

Signature: /__________________________/ Date: __________________
Michael Shur, an individual residing in Latham, NY, US

Signature: /__________________________/ Date: __________________
Remigijus Gaska, an individual residing in Columbia, SC, US

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WHEREAS Assignee desires to obtain all of the rights title, and interest, for all countries in and to the Patent Applications and the inventions and improvements described therein as the sole owner of the Patent Applications.

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Michael Shur, Vice President

By each Inventor:

Signature: /______________________________/ Date: ____________________
Daniel Billingsley, an individual residing in Austin, TX, US

Signature: /______________________________/ Date: 4/14/15
Robert M. Kennedy, an individual residing in Columbia, SC, US

Signature: /______________________________/ Date: ____________________
Wenhong Sun, an individual residing in Columbia, SC, US

Signature: /______________________________/ Date: 04.14.2015
Rakesh Jain, an individual residing in Columbia, SC, US

Signature: /______________________________/ Date: ____________________
Maxim S. Shatalov, an individual residing in Columbia, SC, US

Signature: /______________________________/ Date: ____________________
Alexander Dobrinsky, an individual residing in Loudonville, NY, US

Signature: /______________________________/ Date: ____________________
Michael Shur, an individual residing in Latham, NY, US

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Remigijus Gaska, an individual residing in Columbia, SC, US

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WHEREAS Assignors desire to sell, assign, and transfer all of their rights, title, and interest, for all countries in and to the Patent Applications and the inventions and improvements described therein to Assignee; and

WHEREAS Assignee desires to obtain all of the rights title, and interest, for all countries in and to the Patent Applications and the inventions and improvements described therein as the sole owner of the Patent Applications.

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By each Inventor:

Signature: /______________________________/ Date: __________________
Daniel Billingsley, an individual residing in Austin, TX, US

Signature: /______________________________/ Date: __________________
Robert M. Kennedy, an individual residing in Columbia, SC, US 5

Signature W. Sun /date: 06/05/2015
Wenhong Sun, an individual residing in Columbia, SC, US

Signature: / / Date:
Rakesh Jain, an individual residing in Columbia, SC, US

Signature: / / Date:
Maxim S. Shatalov, an individual residing in Columbia, SC, US

Signature: / / Date:
Alexander Dobrinsky, an individual residing in Loudonville, NY, US

Signature: / / Date:
Michael Shur, an individual residing in Latham, NY, US

Signature: / / Date:
Remigijus Gaska, an individual residing in Columbia, SC, US

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Signature: /____________________/ Date: 04/15/2015
Michael Shur, Vice President

By each Inventor:

Signature: /____________________/ Date: __________
Daniel Billingsley, an individual residing in Austin, TX, US

Signature: /____________________/ Date: __________
Robert M. Kennedy, an individual residing in Columbia, SC, US

Signature: /____________________/ Date: __________
Wenhong Sun, an individual residing in Columbia, SC, US

Signature: /____________________/ Date: __________
Rakesh Jain, an individual residing in Columbia, SC, US

Max Shatalov
Digitally signed by Max Shatalov
DN: cn=Max Shatalov, o=Sensor Electronic Technology, Inc., ou, email=shatalov@s-et.com, c=US
Date: 2015.04.15 10:31:32 -04'00'

Signature: /____________________/ Date: 04/15/2015
Maxim S. Shatalov, an individual residing in Columbia, SC, US

Signature: /____________________/ Date: __________
Alexander Dobrinsky, an individual residing in Loudonville, NY, US

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Signature: /____________________/ Date: ____________
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Signature: /____________________/ Date: ____________
Daniel Billingsley, an individual residing in Austin, TX, US

Signature: /____________________/ Date: ____________
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Signature: /____________________/ Date: ____________
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Rakesh Jain, an individual residing in Columbia, SC, US

Signature: /____________________/ Date: ____________
Maxim S. Shatalov, an individual residing in Columbia, SC, US

Signature: /Alexander Dobrinsky/ Date: 05/11/2015
Alexander Dobrinsky, an individual residing in Loudonville, NY, US

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